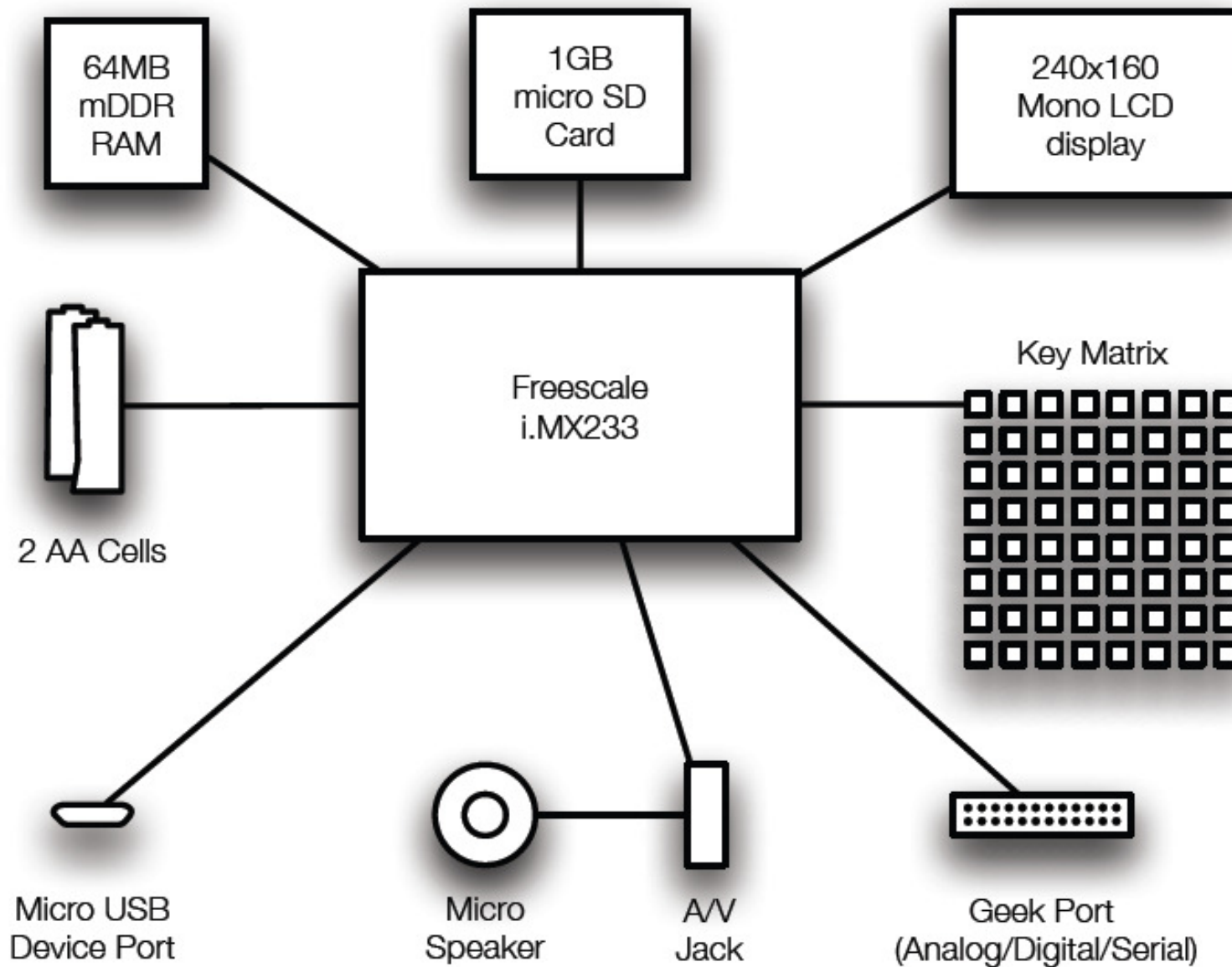


The figure shows a technical drawing of a rectangular plate. The plate is labeled "OPENCALC PA1" in the center. The dimensions of the plate are indicated by numbers 5, 4, 3, 2, and 1 along the top and bottom edges. The plate is also labeled with letters A, B, C, and D along the left and right edges. In the bottom right corner, there is a title block with the following information:

Title	
OPENCALC OC1 TITLE	
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OPENCALC BLOCK DIAGRAM

Title		
OPENCALC OC1 BLOCK DIAGRAM		
Size A	Document Number <Doc>	Rev 1
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Questions

Should DQS have pulldowns on board?

Q. In USB-only power mode is it possible to enumerate at 100mA VBUS current consumption?

A. Our team believes this is possible, but is not supported by default in the BSP today. Using mobile DDR would be recommended to achieve this reliably.

Q. PSWITCH recovery vs. regular USB mode: Is there any difference between the USB boot mode (selected by the boot mode pins) and the recovery mode (selected by the PSWITCH) mode? Is this simply 2 ways of entering the same USB mode?

A. Yes, these are equivalent. PSWITCH is is just the manual entry into USB recovery mode. You can also enter USB recovery mode if there is a non-recoverable boot time error. Of course the bootmode switches can land you here as well.

Q. What's the fundamental difference between the application UART and the debug UART? Does the debug UART have any special function in the various boot modes? Or is it simply a difference in speed it's capable of?

A. The debug UART is limited to 115.2Kbps with no flow control pins available in either package. The application UART's are capable of 3.25Mbps with one UART having flow control pins available in the 169 pin BGA, though not in the QFP.

Q. Does the DC-DC only run off of 4.2V? that is: can we connect 5V to the 4.2V supply directly and avoid loosing the 0.8V drop in efficiency? ABS MAX ratings show VDD4P2V maximum at 4.242. Is that a hard requirement?

A. When using a 5V supply the 4P2 regulator is a hard requirement. Again AN3989 can shed a little light on the situation.

Q. Have customers successfully implemented the MX233 in QFP on 4 layer boards and met EMI? Seems like it may be a bit of a challenge.

A. Per AN3883 it can be done but ESD performance will be compromised. See the attached copy. I will also ask the factory to see if they can provide any more information.

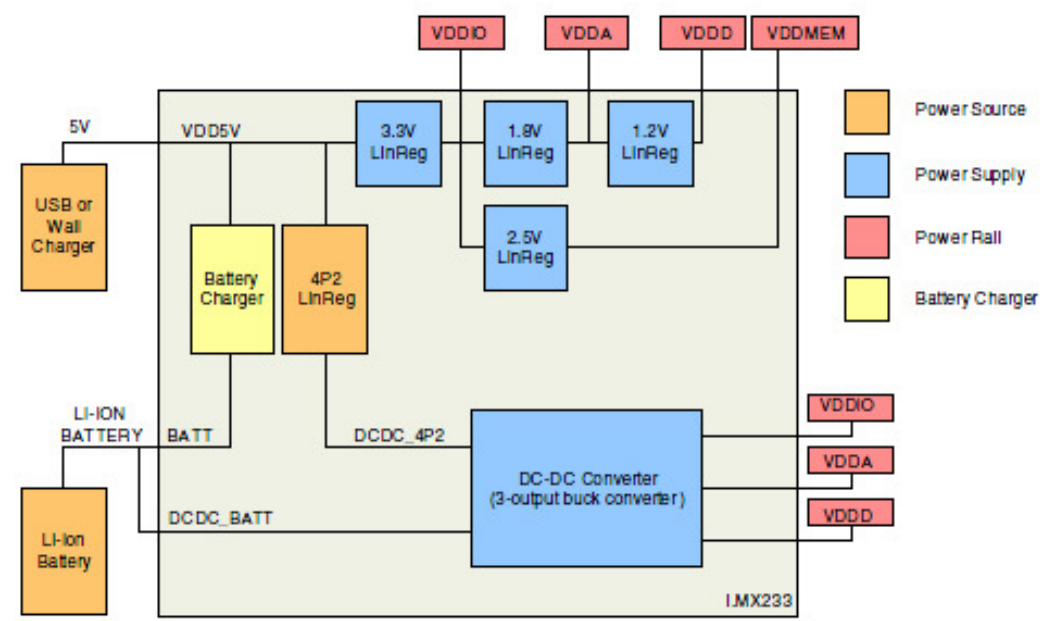


Figure 1. Logical Diagram of i.MX233 PMU

Title		
OPENCALC OC1 DESIGN NOTES		
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Changelist

6/25/2011: Initial Revision

TODO

- put protection on the SD port
- put detection on the headset port.

MX233 Port Usage

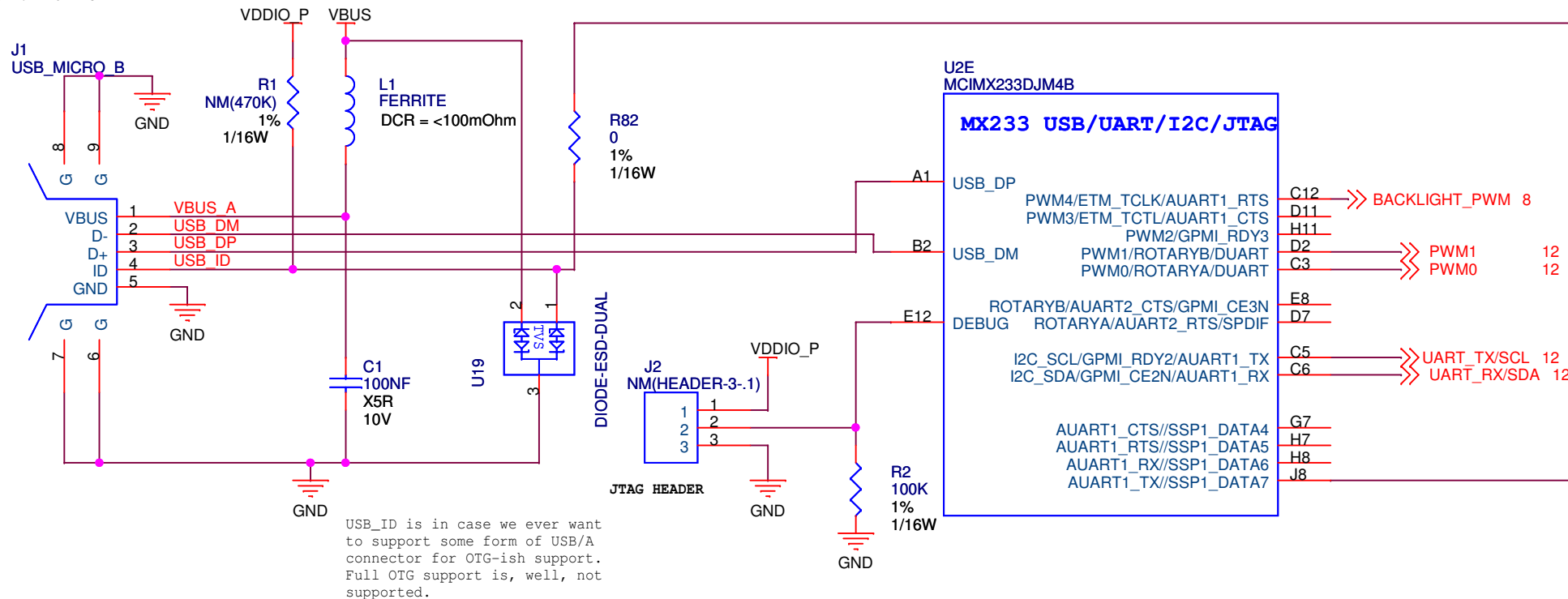
- * I2C/AUART1 -> GEEK PORT
- * AUART2 (ALL 4 PINS) -> RESERVED FOR BLUETOOTH
- * EMI -> mDDR
- * SSP1 -> uSD card
- * LCD -> LCD
- * SAIF -> GEEK PORT gpio pins

Title		
OPENCALC OC1 CHANGELIST		
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Layout Note: Low impedance Vias to GND! for ESD

Ferrites, CMC and ESD diode examples from murata applications guide, and intel guide in 'docs' directory.

USB/CRYSTAL/JTAG

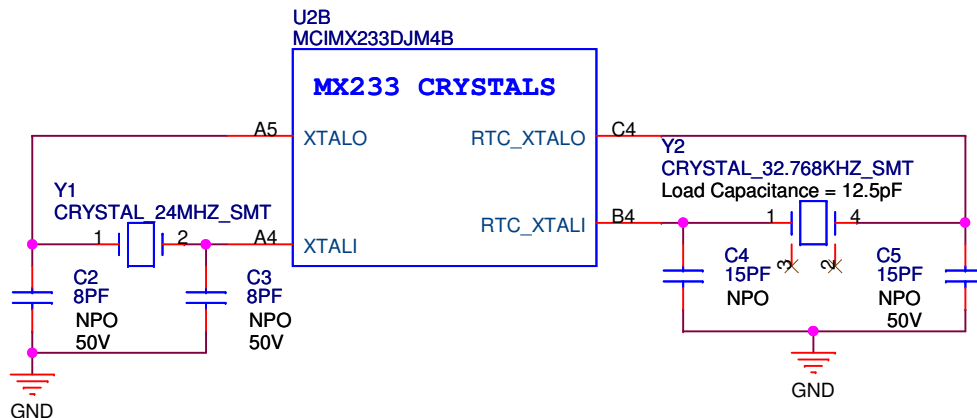


Crystal Design Notes:
The 24 MHz crystal should be located close to the mx25.

$$\text{Cload} = [(C1 \cdot C2) / (C1 + C2)] + C_{\text{stray}}$$

$C_{\text{stray}} \approx 4\text{-}6\text{pF}$

Set $C1 == C2$:
 $\text{Cload} = (C1^2 / 2C1) + C_{\text{stray}}$
 $\text{Cload} = C1 / 2 + C_{\text{stray}}$
 $C1 = 2 * (\text{Cload} - C_{\text{stray}})$
 $C1 = C2 = 2 * (8\text{pF} - 4\text{pF}) = 8\text{pF}$



Title		
OPENCALC OC1 USB & OSCILLATORS		
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U2C
MCIMX233DJM4B

MX233 DDR

EMI_CLK	M6	DDR_CLK	G2
EMI_CLKN	N6	DDR_CLKN	G3
EMI_DQS1	K8	DDR_DQS1	E2
EMI_DQS0	N12	DDR_DQS0	E8
EMI_CASN	M13	DDR_CASN	G8
EMI_RASN	N13	DDR_RASN	G9
EMI_CE0N	J10	DDR_CE0N	H7
EMI_CE1N	H12		
EMI_CKE	F11	DDR_CKE	G1
EMI_WEN	J11	DDR_WEN	G7
EMI_BA1	L12	DDR_BA1	H9
EMI_BA0	L13	DDR_BA0	H8
EMI_DQM1	M9	DDR_DQM1	F2
EMI_DQM0	M12	DDR_DQM0	F8
EMI_D15	M7	DDR_DQ15	A2
EMI_D14	N7	DDR_DQ14	B3
EMI_D13	K6	DDR_DQ13	B2
EMI_D12	L7	DDR_DQ12	C3
EMI_D11	K7	DDR_DQ11	C2
EMI_D10	M8	DDR_DQ10	D3
EMI_D09	N8	DDR_DQ9	D2
EMI_D08	N9	DDR_DQ8	E3
EMI_D07	L9	DDR_DQ7	E7
EMI_D06	L11	DDR_DQ6	D8
EMI_D05	K9	DDR_DQ5	D7
EMI_D04	M11	DDR_DQ4	C8
EMI_D03	N10	DDR_DQ3	C7
EMI_D02	N11	DDR_DQ2	B8
EMI_D01	M10	DDR_DQ1	B7
EMI_D00	K10	DDR_DQ0	A8
EMI_A12	H13	DDR_A12	F7
EMI_A11	H10	DDR_A11	H3
EMI_A10	J12	DDR_A10	H2
EMI_A09	F13	DDR_A09	J7
EMI_A08	G13	DDR_A08	H1
EMI_A07	G11	DDR_A07	J3
EMI_A06	F12	DDR_A06	J2
EMI_A05	G12	DDR_A05	J1
EMI_A04	G10	DDR_A04	K3
EMI_A03	K11	DDR_A03	K2
EMI_A02	J13	DDR_A02	K8
EMI_A01	K12	DDR_A01	K7
EMI_A00	K13	DDR_A00	K9

Layout Note: DDR_DQ[15:8]
and DDR_DQ[7:0] can be
shuffled within any byte for
layout convenience.

R4
10.0K
1%
1/16W

R5
10.0K
1%
1/16W

MDDR1,32MX16,VFBGA

LAYOUT NOTE: CONTROL #of vias on DQx, DQS and CLK.

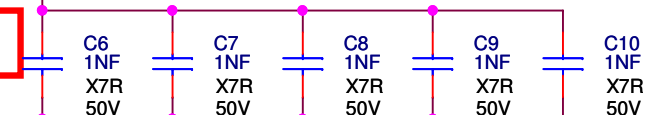
VDDQ A7
VDDQ B1
VDDQ C9
VDDQ D1
VDDQ E9
VDD A9
VDD F9
VDD K9

VSS A1
VSS F1
VSS K1
VSSQ A3
VSSQ B9
VSSQ C1
VSSQ E1

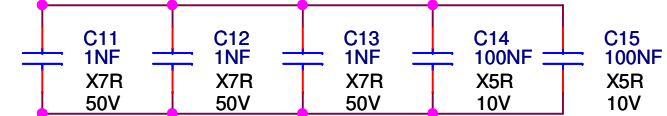
TEST D9

NC F3

VDDIO_DRAM



VDDIO_DRAM



* MDDR parts from Micron:
All in 60-ball package

MT46H128M16LFCK	2	Gb / 256 MB
MT46H64M16LFBF	1	Gb / 128 MB
MT46H32M16LFBF	512	Mb / 64 MB
MT46H16M16LFBF	256	Mb / 32 MB
MT46H8M16LFBF	128	Mb / 16 MB

VDDIO_DRAM VDDA VDDM

NOTE: MDDR/DDR DIFFERENCES

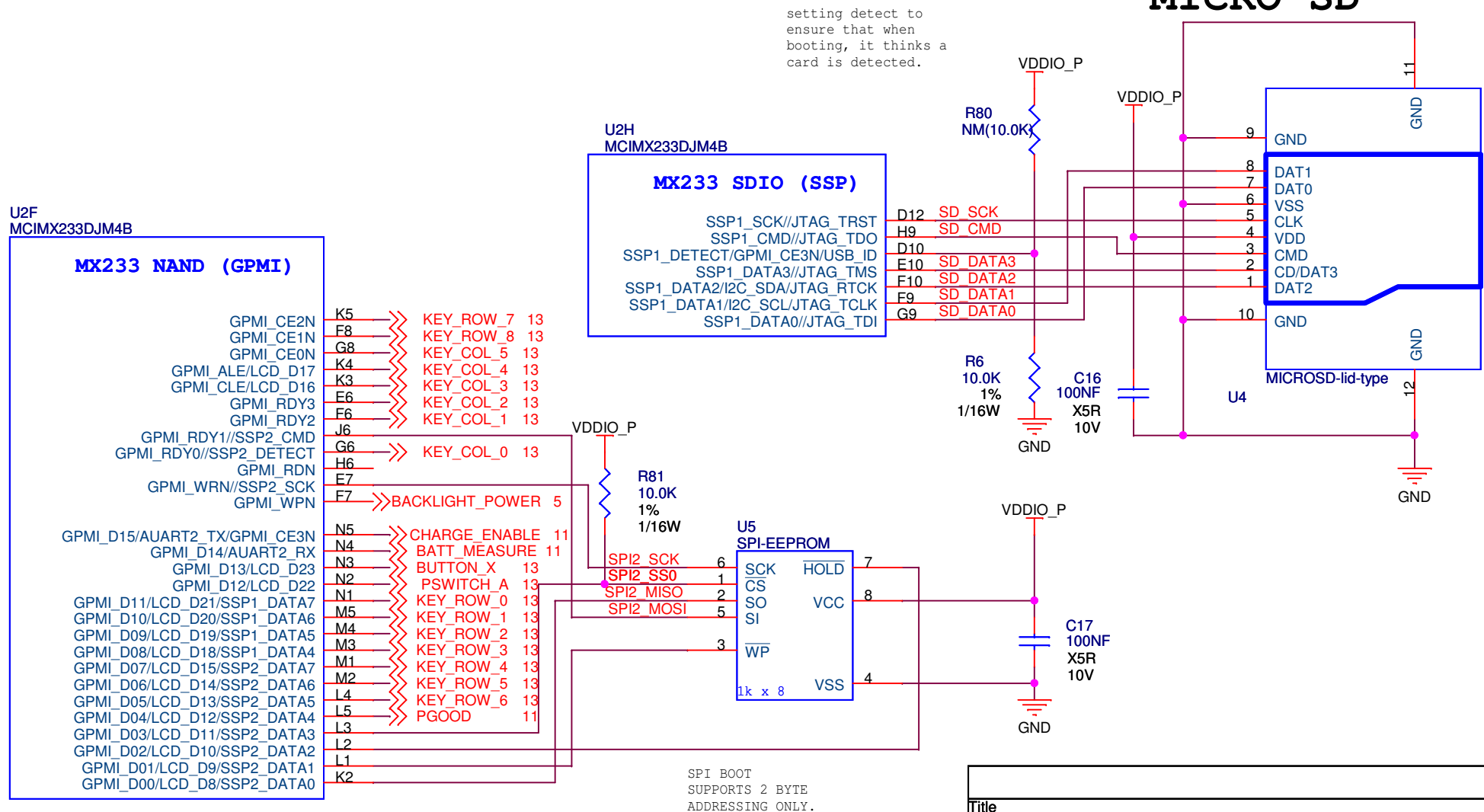
FOR MDDR: VDDIO_DRAM == VDDA & PULLUP/DN = 10.0K
FOR DDR: VDDIO_DRAM == VDDM * PULLUP/DN = 47K

DDR and mDDR are NOT pin compatible unfortunately.
You must choose.

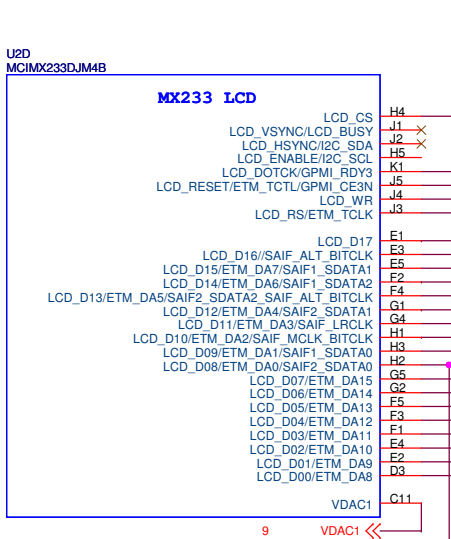
Title Opencalc mDDR		
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FLASH

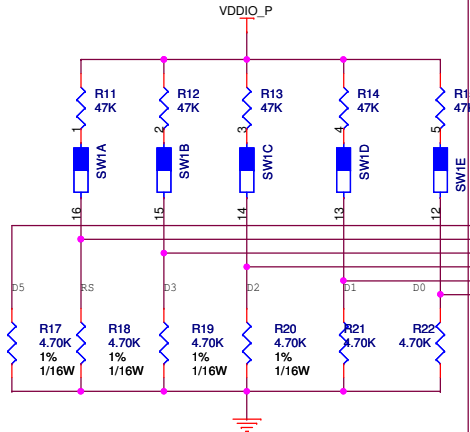
MICRO SD



Title		
OPENCALC OC1 FLASH		
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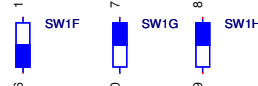
AS Per IMX233RM, page 2-7, table 2-8, 50K resistor is sufficient to overcome the pin keeper.



BOOT: Default to I2C Boot.

	D5	RS	D3	D2	D1	D0
USB	0	1	0	0	0	0
3.3V I2C MASTER	0	1	0	0	0	1
3.3V SPI FLASH 1 MASTER	0	1	0	0	1	0
3.3V SPI FLASH 2 MASTER	0	1	0	0	1	1
3.3V NAND	0	1	0	1	0	0
DEBUG	0	1	0	1	1	0
3.3V SD/MMC 1	0	1	1	0	0	1
3.3V SD/MMC 2	0	1	1	0	1	0
BOOT MODE FROM OTP	0	0	X	X	X	X
ETM ENABLE	1					

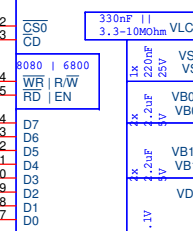
BOOT NOTE:
Due to a bug in the SD Boot process (see errata), we need to boot from an I2C boot device, which patches the boot code to then boot from SD card.



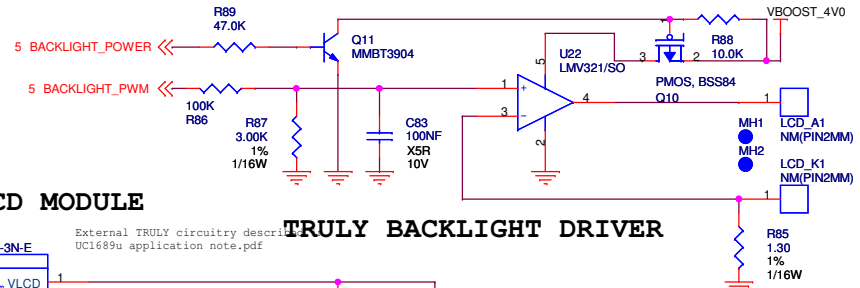
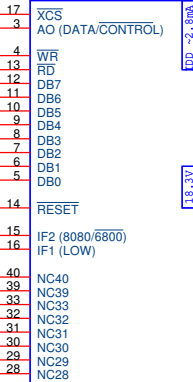
LCD INTERFACE

TRULY LCD MODULE

U6
LCD-MFG-G240160DPSW-3N-E

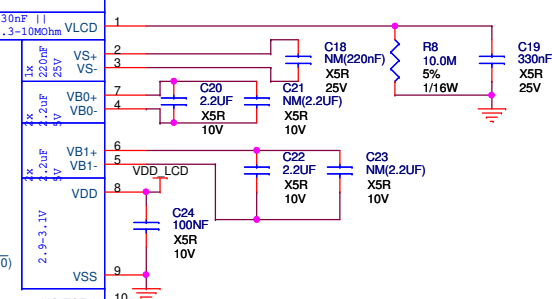


U7
LCD-ASUJ24016GFCIDI.PDF

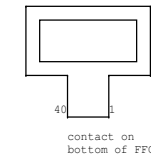
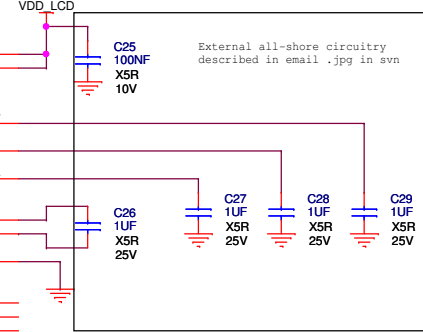


TRULY BACKLIGHT DRIVER

External TRULY circuitry described in UC1689u application note.pdf



Extra resistor in inverting loop to ensure that even with input offset voltage, that when backlight_pwm is low, that pin 3 is HIGHER than pin 1 of op amp.

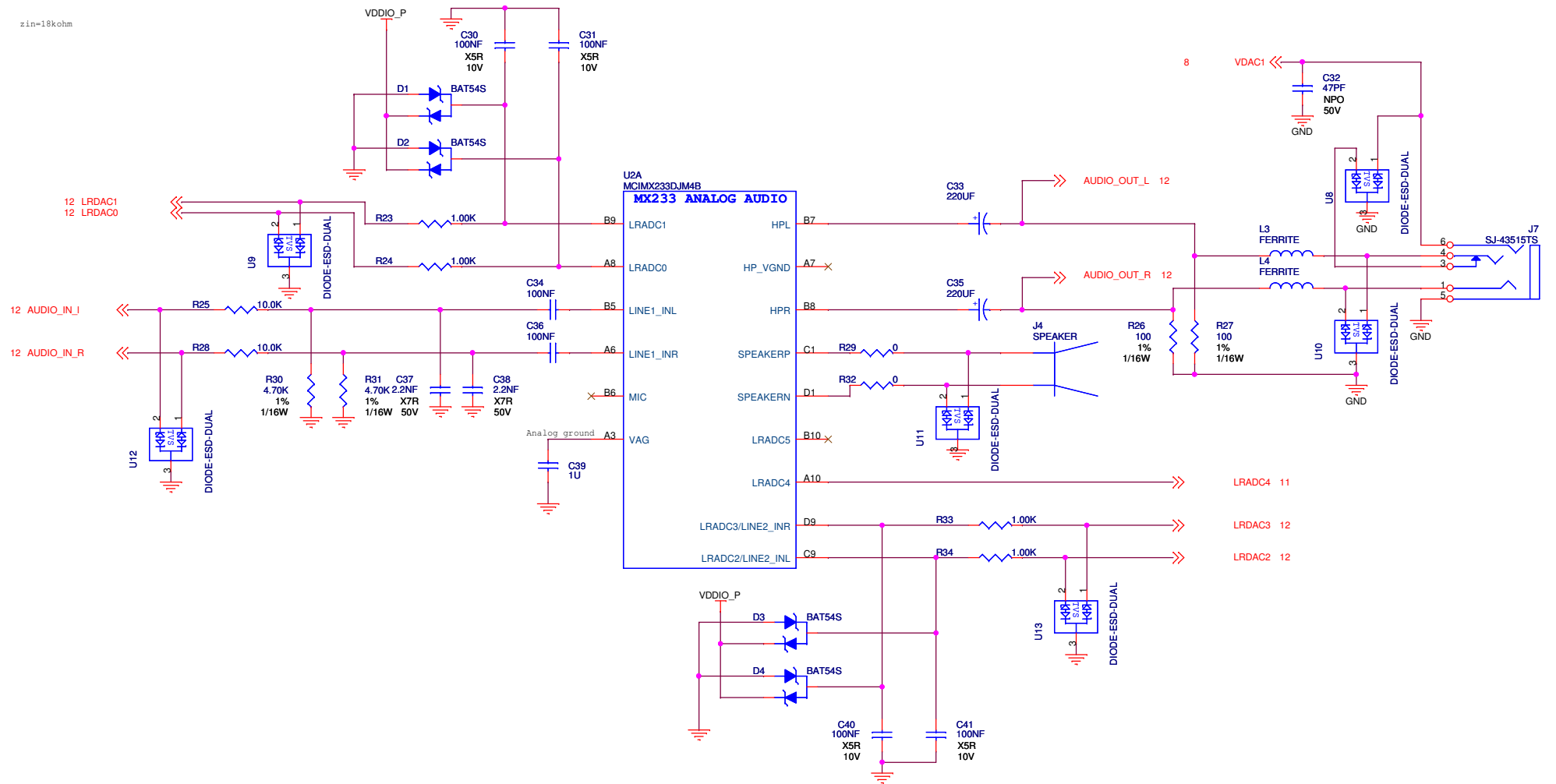


Title OPENCALC OC1 LCD AND BOOT		
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LRADC NOTES
 * Ch 15 = VDD5V
 * Ch 14 = bandcap ref.
 * Ch 12&13 = USB DP and DN
 * Ch 9&8 = die temp.
 * Ch 7 = BATT pin
 * Ch 6 = VDDIO

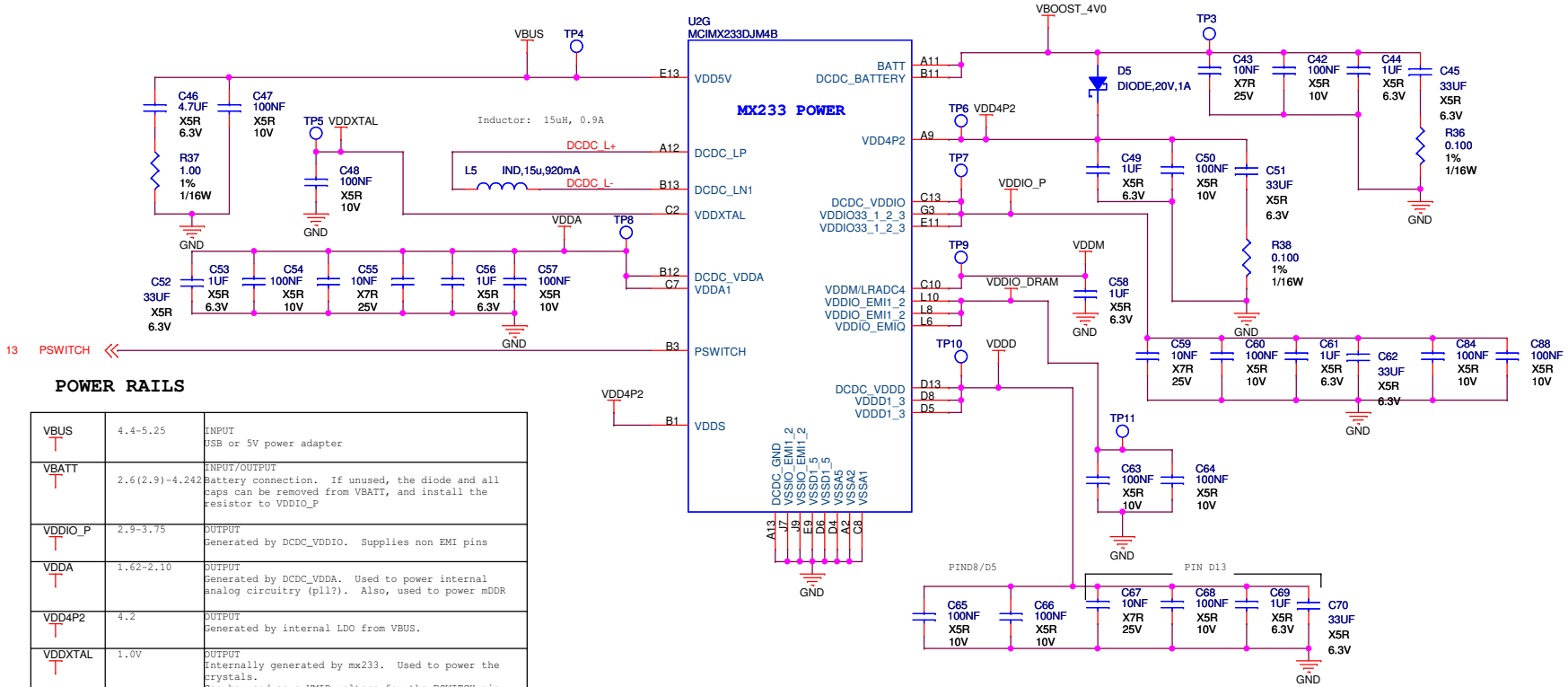
VMAX = 1.85V

zin=18kohm



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OPENCALC OC1 AUDIO		
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POWER

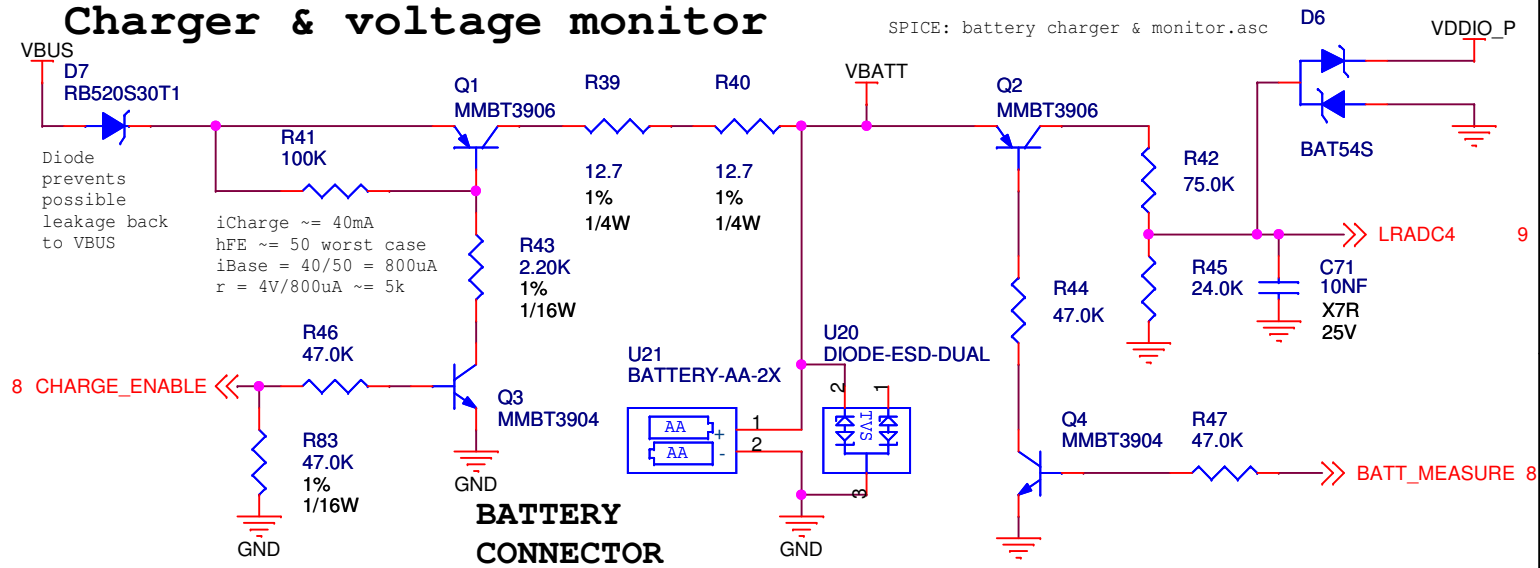


Title		
OPENALC OC1 POWER		
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Charger & voltage monitor

SPICE: battery charger & monitor.asc

VBATT = 2.0 - 3.2
 C = 2200 mAh
 C/30 = 73mA
 VBUS = 5.0 nom
 Ifinal = 73mA
 $R = V/I = (5-3.2)/73mA = 25 \text{ Ohms}$
 $P_{max} = (5.25 - 2.0)^2/25 = 0.42 \text{ Watts}$
 $P_{final} = (5.25 - 3.2)^2/25 = 0.17 \text{ Watts}$
 $I_{initial} = (5.25 - 2.0)/25 = 130mA$
 $I_{final} = (5.25 - 23.2)/25 = 82mA$



Battery (1.8 to 5.25 possible) to VBOOST_4V0

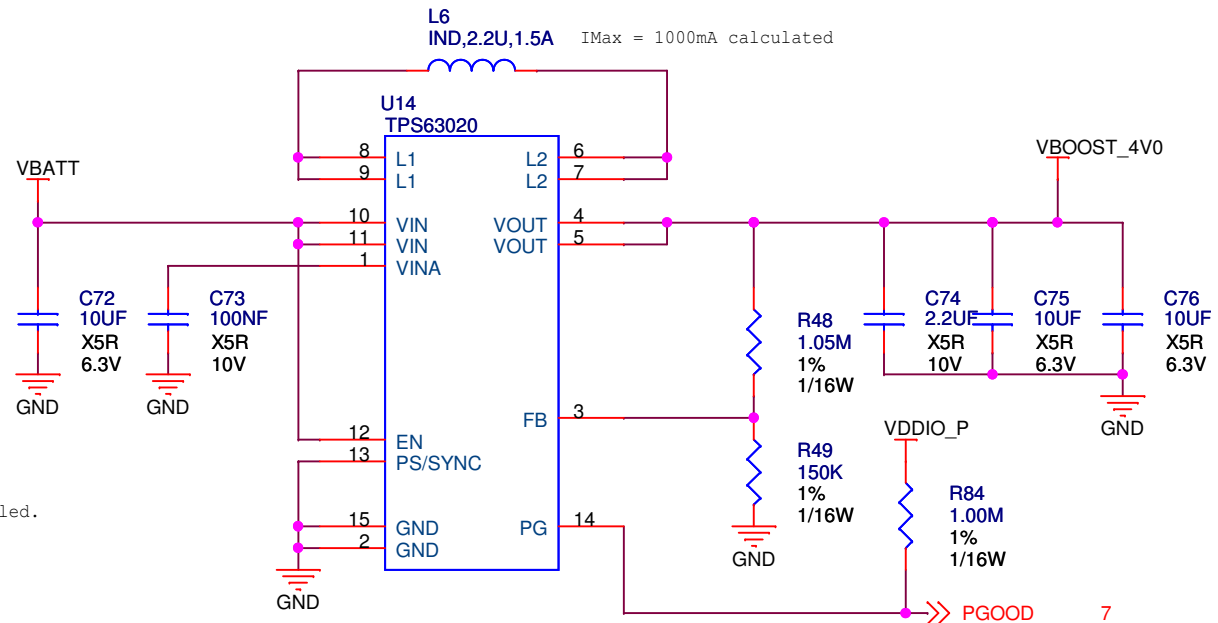
Vin1: 5.25;
 Vin2: 1.8;
 Iout: 600e-3;
 fr: 2.4;
 Vout: 1.2;
 $L1: (Vin1 - Vout) * .5;$
 $L2: Vout * .5;$
 $L: \max(L1, L2);$
 $L: 2.2;$
 $I1: Iout / (.8 + Vout * (Vin1 - Vout) / (2 * Vin2 * fr * L));$
 $I2: Vout * Iout / (.8 * Vin2) + Vin2 * (Vout - Vin2) / (2 * Vout * fr * L);$
 $I_{max} = \max(I1, I2);$
 $C_{out} = 10 * L;$

Battery only:
 All system power is provided through the boost regulator.
 USB plugged in:
 All system power comes through VBUS.
 USB+BATT:
 All system power comes through VBUS. Battery charging enabled.

TPS63020 LEAKAGE = 25 uA typ
 MX233 LEAKAGE = 11 uA typ when shut down

So, that looks like 40 uA to be safe for boost + mx233.
 $1200e3 \text{ uA-h} / 40 \text{ uA} = 3.4 \text{ years}$ on a full charge before depletion. This should be less than the internal leakage for all except the best NiMH batteries. Not as good as Alkaline.

$R1 = R2 * (Vout/Vfb - 1);$
 $R2 = 150k;$
 $Iout = Vfb/R2 = 0.5/150k = 3.33333uA$
 $Vout = 4.0V$
 $R1 = (4.0-0.5)/3.33333uA = 1.05mOhm$



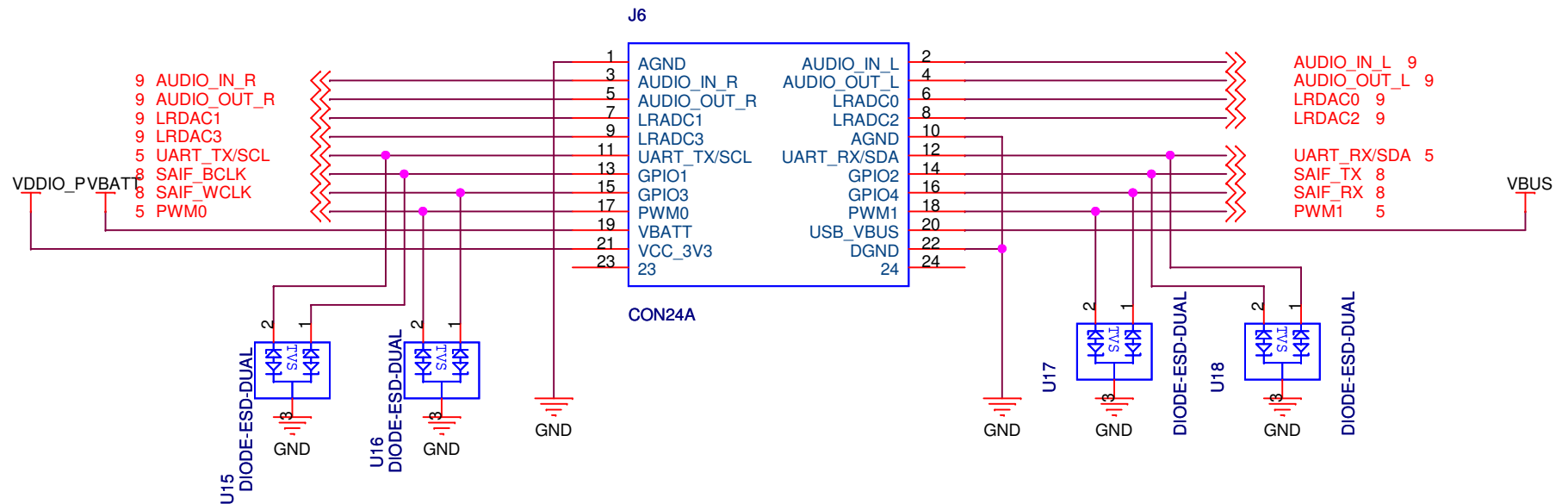
Title		
OPENCALC OC1 BATTERY & BOOST CONVERTER		
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GEEK PORT

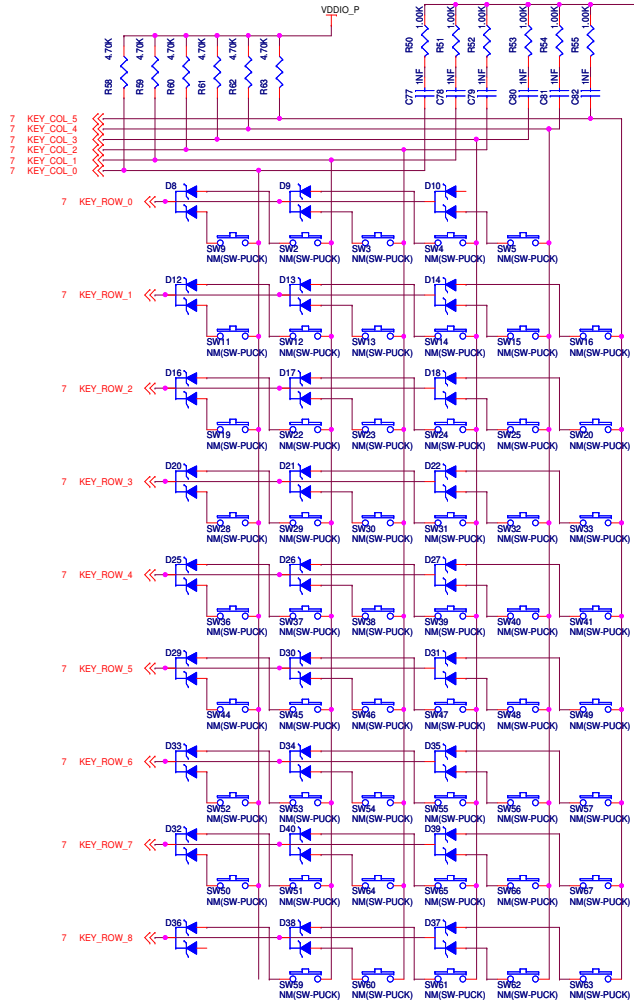
* TODO: IO protection on geek port pins

* All pins must be protected during system power off. This means that even when VDDIO_P is 0 V, no pin (at the CPU) is allowed to exceed VDDIO_P + 0.3 V, and GND - 0.3V. This will require something like a resistor + schottky at each pin.

This can get tricky for analog pins.



Title		
OPENCALC OC1 GEEK PORT		
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KEYPAD MATRIX

Keyscan Technique:
Software must drive rows low, and set col lines to input, interrupt whenever a column line goes low. (or poll, that's fine too)
Then, when a column line goes low, to determine which key has been pressed, in the ISR sequence through each row with one-row-high and see which col line toggles.
Any col lines that go high is pressed. The diodes prevent shorting 2 row and 2 col lines directly.

No ESD protection required if keymat can be made without locating holes. Is it possible to make the keymat holes just indentations?

NOTE: These caps are to keep the contacts clean, not to do any debouncing.

10K SPECIFIED IN DATASHEET

NOTE: PSWITCH must have a falling edge SLOWER than 15ns to prevent power off when PSWITCH pressed.

PSWITCH_A is not strictly necessary -- the PSWITCH pin state can be polled from software. But this lets it operate simply from an interrupt.

PSWITCH STATES:
* If PSWITCH > min (MID) for > 100ms, then power on
* If PSWITCH has a falling edge faster than 15ns, power OFF
* If PSWITCH > min(MID), lower bit of RM_POWER_STS_PSWITCH is set.
* If PSWITCH is pulled to VDDIO via a resistor, upper bit of RM_POWER_STS_PSWITCH is set.
* If PSWITCH is pulled to VDDIO during initial boot sequence for more than 5 seconds, PW recovery mode is entered.

LOW: 0 < PSWITCH < 0.30
MID: 0.65 < PSWITCH < 1.5
HIGH: 2.1 < PSWITCH < VDDXtal+1.575 = 2.575
VDDXtal: ~ 1V
VDDIO: ~3.3

